

Graduate-Level Research in Industrial Projects for Students
JUNE 19 - AUGUST 8 2023

Overview

Graduate-Level Research in Industrial Projects for Students (G-RIPS) in Sendai will offer graduate students in mathematics and related disciplines the opportunity to work on industry-sponsored research problems in Sendai, Japan. Students from the U.S. and Japan will work on crosscultural teams on research problems designed by industrial sponsors. The projects will be of serious interest to the sponsor and will offer a stimulating challenge to students; most will involve both analytic and computational work. At the end of the program, the teams will present the results of their work and prepare a final report. IPAM will encourage the U.S. students to publish and/or present their research at conferences in the year following the program. English is the only language required for participation.

Partner

G-RIPS Sendai will be held at the Advanced Institute for Materials Research (AIMR) at Tohoku University in Sendai, Japan. Sendai is located 300 km north of Tokyo and 1.5 hours by high-speed train. Tohoku University is the third oldest Imperial University and considered one of the most prestigious universities in Japan.

Sponsors

The industrial partners for G-RIPS Sendai 2022 included: Mitsubishi Electric Corporation, NEC Corporation, and F-MIRAI. Details about the 2023 industrial partners and projects will be announced on the program web page.

Benefits

Round-trip travel to Sendai and accommodations in Sendai are included. Students will also receive a meal allowance, a stipend, and travel support to present their research at a conference. (These terms apply to U.S. participants recruited by IPAM.)

Application

Eligible applicants include graduate students in math or a related discipline, with a preference given to students in their second or third year of a PhD program. IPAM will only accept applications from U.S. citizens and permanent residents; Japanese students are encouraged to contact Tohoku University for information and an application. The application will open in January 2023. The deadline to apply is February 24, 2023.





